

NEGATIVE PHOTOSENSITIVE RESIN COMPOSITION, NEGATIVE PHOTOSENSITIVE RESIN COMPOSITION FILM, CURED PRODUCT, PREPARATION METHOD OF CURED PRODUCT, HOLLOW STRUCTURE, AND ELECTRONIC COMPONENT

ABSTRACT

It is intended to provide a negative type photosensitive resin composition that ensures high aspect ratio pattern processability, high storage stability, and high curability and also provides a cured product with good mechanical characteristics and high heat resistance. A negative type photosensitive resin composition comprising a polymer compound (A), a cationic polymerizable compound (B), a cationic polymerization initiator (C), and a solvent (D) wherein the component (A) contains at least one compound selected from the group consisting of polyamide, polyimide, polybenzoxazole, precursors thereof, and copolymers thereof and wherein both the relations $0.6A \leq B + 0.5C \leq 0.98A$ and $0.05(B + C) \leq C \leq 0.25(B + C)$ are satisfied where A (moles), B (moles), and C (moles) represent the quantities of all carboxylic acid residues, all diamine residues, and all monoamine residues, respectively, contained in the component (A).

[No suitable figure]